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Alexei Nikitin, Avatekh, USA; Arlie Stonestreet II, Kyle D. Tidball, Ultra Electronics ICE, USA; Ruslan L. Davidchack, University of Leicester, UK

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Markus Makoschitz, AIT Austrian Institute of Technology, AT; Michael Hartmann, Schneider Electric, AT; Hans Ertl, Vienna University of Technology, AT

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Tom Ribarich, Stephen Oliver, Navitas Semiconductor, USA

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Akihiro Osawa, Keiichi Higuchi, Akio Kitamura, Daisuke Inoue, Yoshikazu Takamiya, Souichi Yoshida, Hiromichi Gohara, Masahito Otsuki, Fuji Electric, J

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Zarina Davletzhanova, Olayiwola Alatise, Jose Ortiz Gonzalez, Sylvia Konaklieva, Roozbeh Bonyadi, University of Warwick, GB

**High Efficiency and Ruggedness Intelligent IGBT Technology for EV/HEV**

Vittorio Crisafulli, ON Semiconductor, D

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Yun Li, Shiwu Zhu; Yaing Ma, Yangang Wang, Mingliang Jiao, Chundong Wu, Zhenlong Zhao, Jun Yu, Dynex Semiconductor, GB

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Leandro Percebon, Daniel Kuerschner, Qualcomm CDMA Technologies, D

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**DC/DC-Converter with Optimised Power Density for Integration of Multifunctional Fuel Cell Systems in Modern Aircraft Application**

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Cristian Vargas, Simon Feuersänger, Mario Pacas, University of Siegen, D

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Giovanni De Carne, Marius Langwasser, Xiang Gao, Giampaolo Buticchi, Marco Liserre, Christian-Albrechts-University, D

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Markus Schnell, Jörg Oehmen, Infineon Technologies, D

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